



Material Content Data Sheet



Halogen-Free

Sales Product Name	AIKB30N65DH5	Issued	06. July 2021
MA#	MA001837606		
Package	PG-TO263-3-2	Weight*	1561.09 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip_1	inorganic material	silicon	7440-21-3	1.783	0.11	0.11	1142	1142
chip_2	inorganic material	silicon	7440-21-3	0.831	0.05	0.05	532	532
leadframe	inorganic material	phosphorus	7723-14-0	0.091	0.01		59	
	non noble metal	iron	7439-89-6	0.304	0.02		195	
	non noble metal	copper	7440-50-8	304.026	19.48	19.51	194753	195007
wire	non noble metal	aluminium	7429-90-5	10.203	0.65	0.65	6536	6536
encapsulation	inorganic material	zincoxide	1314-13-2	6.824	0.44		4371	
	miscellaneous	miscellaneous	-	27.295	1.75		17484	
	plastics	epoxy resin	-	102.355	6.56		65567	
	inorganic material	silicondioxide	60676-86-0	545.893	34.97	43.72	349689	437111
leadfinish	non noble metal	tin	7440-31-5	9.657	0.62	0.62	6186	6186
plating	inorganic material	phosphorus	7723-14-0	0.001			1	
	non noble metal	nickel	7440-02-0	0.228	0.01	0.01	146	147
solder	non noble metal	tin	7440-31-5	0.064			41	
	noble metal	silver	7440-22-4	0.080	0.01		52	
	non noble metal	lead	7439-92-1	3.072	0.20	0.21	1968	2061
heatspreader	inorganic material	phosphorus	7723-14-0	0.165	0.01		105	
	non noble metal	iron	7439-89-6	0.548	0.04		351	
	non noble metal	copper	7440-50-8	547.666	35.07	35.12	350822	351278
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 Neubiberg
Internet	www.infineon.com